

OPTICAL AND ELECTRONIC SOLUTIONS FOR
TESTING AND FAILURE ANALYSIS

Single-Photon and Two-Photon correlation case study on digital devices

Sébastien Jonathas

PULSCAN

sebastien.jonathas@pulscan.com



Outline

- Motivation
- Devices under test (DUT)
- Test setup
- PULSCAN laser system
- Experimental results
 - ▶ SRAM
 - ▶ MRAM
- Conclusions

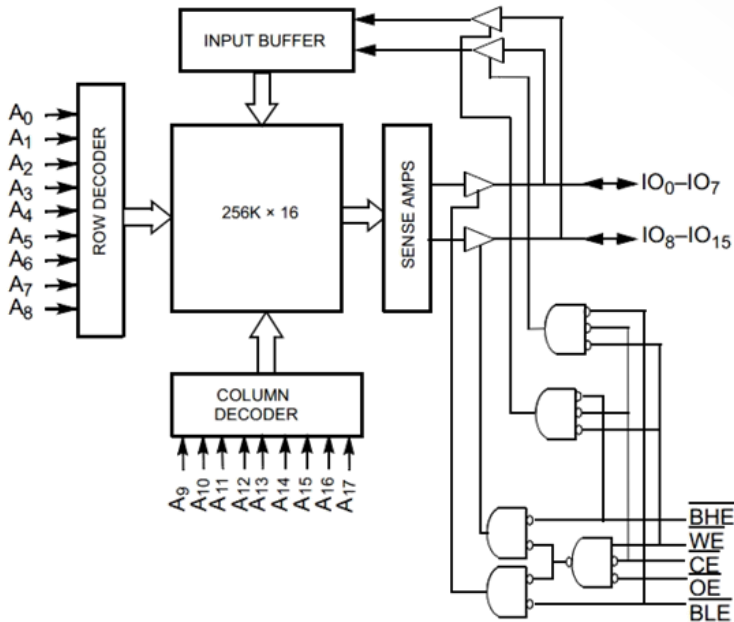


Motivation

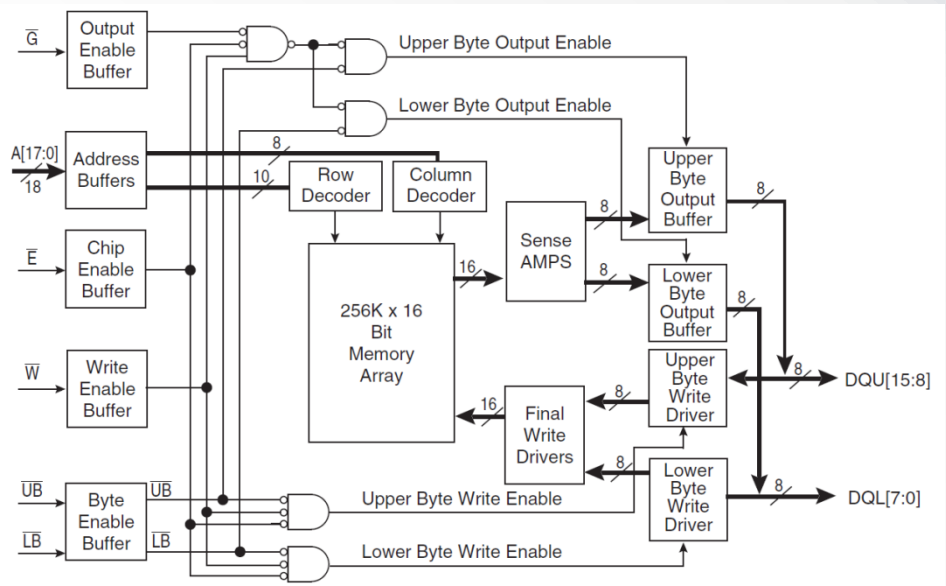
- Demand on laser testing is raising up
- Recurent question: reference data and/or calibration
- Provide additional laser testing results to the community
- Measure SEU and SEL laser energy threshold on COTS memories with SPA and TPA laser system
- Compare SPA and TPA laser energy for different Single Event

Devices Under Test (DUT)

DUT	Manufacturer	Part Number	Package	Power supply voltage (Typ.)	Capacity	Technology	Substrate thickness
SRAM	Cypress	CY7C1041DV33	TSOP11-44	3.3V	4-Mbit	90nm	246μm
MRAM	E2V	EV2A16A	TSOP11-44	3.3V	4-Mbit	180nm	40μm



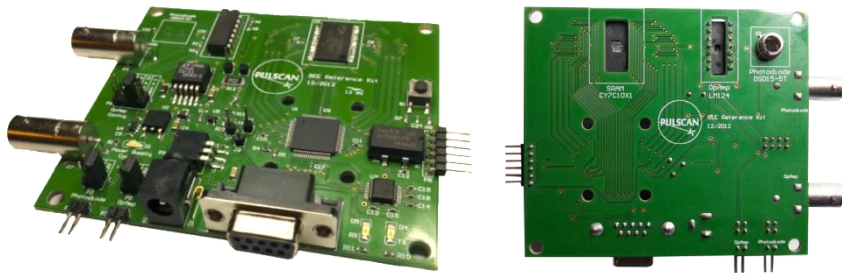
SRAM CY7C1041DV33 – Block diagram



MRAM EV2A16A – Block diagram

Test setup

- Two test boards:
 - ▶ SRAM : PULSCAN SEE Reference Kit;
 - ▶ MRAM : Xilinx dev board + PULSCAN daughter board.
- Both boards include a current limiter to protect the DUT from destructive SEL (power supply recycling):
- Each board has its dedicated software to initialize the DUT, detect and report different types of events.



PULSCAN SEE Reference Kit

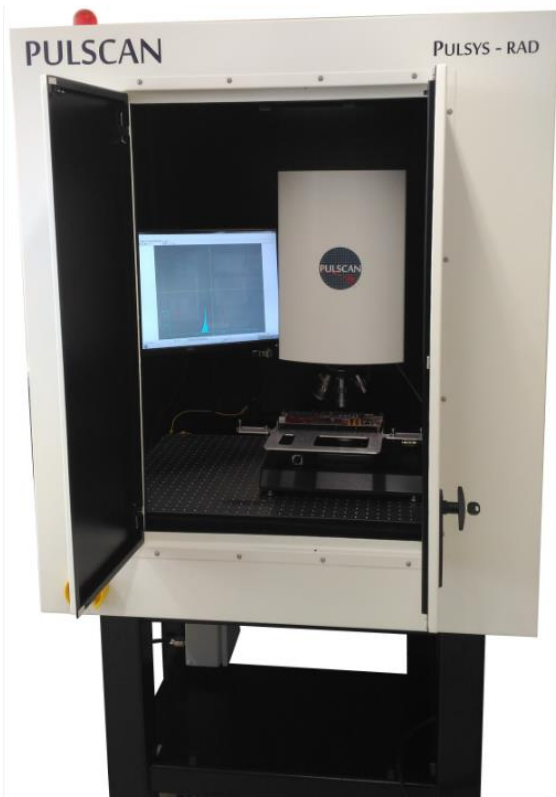


Xilinx AC701 + Daughter board



PULSCAN laser system (PULSYS-RAD)

PULSYS main frame
Laser injected Infrared microscope

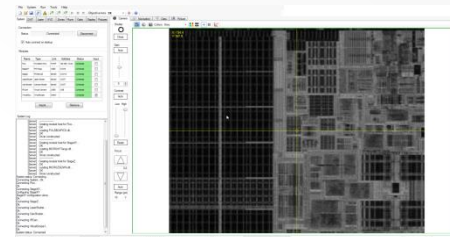
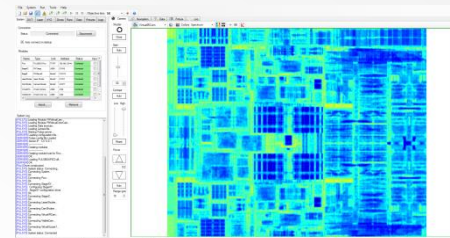
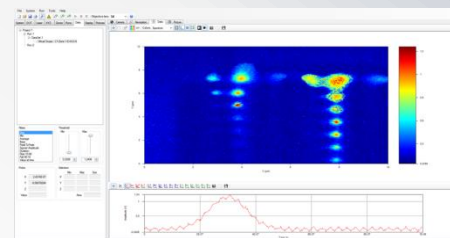


PULSBX Pico/2P
Smart laser source

PULSBX	Pico	2P
Absorption mechanism	SPA	TPA
Wavelength	1064nm	1550nm
Pulse duration	30ps	450fs
Maximum Energy at the fiber output	50nJ	50nJ



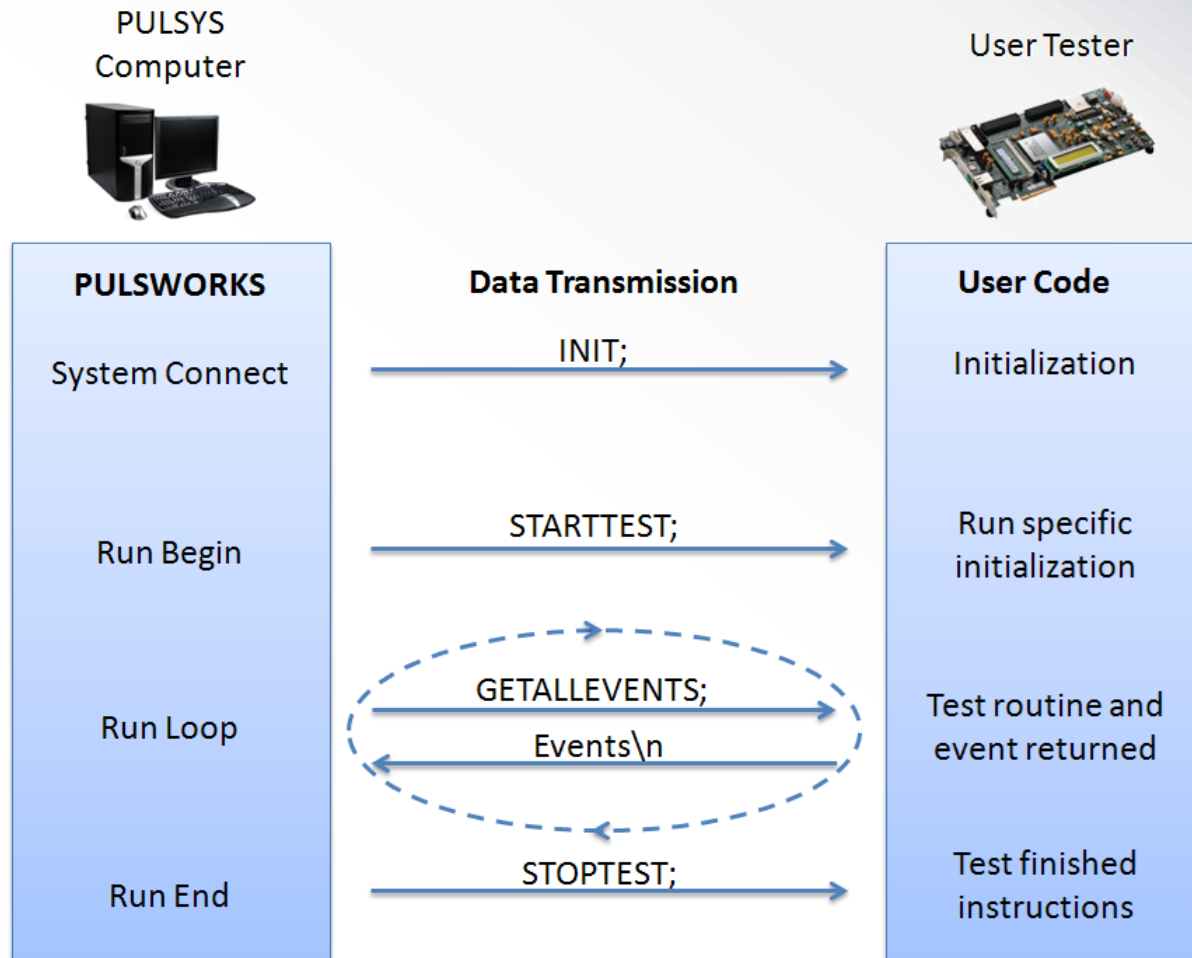
PULSWORKS
Laser testing dedicated software





PULSYS-RAD and test board communication

Typical test procedure





Data analysis with PULSWORKS

The screenshot displays the PULSWORKS software interface. The main window shows a heatmap of data points on a 5x5 grid. The X and Y axes are labeled in micrometers (μm) and range from 0 to 5. A color scale on the right indicates values from 0 (dark blue) to 8 (red). A red circle with a crosshair is centered on the data point at approximately (3.2, 2.2).

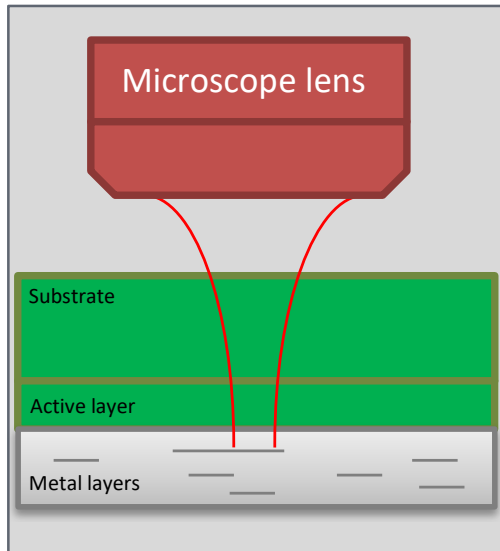
The interface includes several control panels:

- Project 1:** Run 1, DataSet 1, containing three test configurations: PMTester.Basic-Zone 1-E=0-Z=0.0, PMTester.Complete-Zone 1-E=0-Z=0.0, and PMTester.DEMO_MAD_FORMAT-Zone 1-E=0-Z=0.0.
- Filters:** A list of filter options including First integer, Second integer, String length, Number of lines, MAD_Address_AND, MAD_Address_NAND, MAD_Address_XOR, MAD_Data_AND, MAD_Data_NAND, and MAD_Data_XOR.
- Threshold:** Sliders for Min (0.0000) and Max (8.0000).
- Probe:** Input fields for X, Y, Z, and Value.
- Selection:** Input fields for X, Y, Z, and Area.
- Bit index:** A dropdown menu set to 0.
- Bit mask:** Input fields for Address, 1s, and 0s, with an Edit button.
- Data:** Input fields for 1s and 0s, with an Edit button.
- Point log:** A list of hexadecimal data points, such as 0x00000000000000AE, 0x22000400, 0x00000000000000AB, 0x01008000, 0x00000000000000AC, 0x04008000, 0x00000000000000AB, 0x00008000, 0x00000000000000AF, 0x00000001, 0x00000000000000A7, 0x00000090, 0x00000000000000A7, 0x11000000, 0x00000000000000B0, 0x00000600.

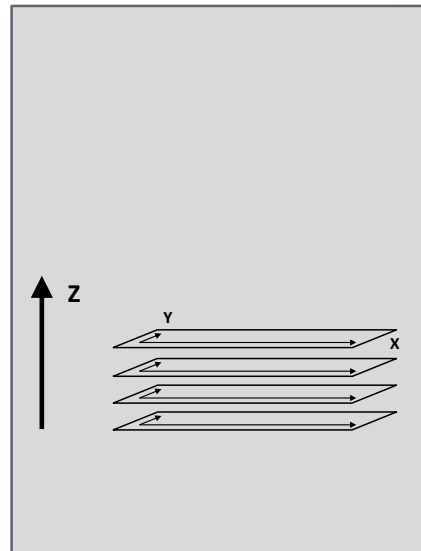
The status bar at the bottom shows: System: Connected, Laser: [off], X:5.0 Y:-1.2 Z:0.0, Run: Done, and Memory usage: 43 MB.

SRAM: SEU threshold energy

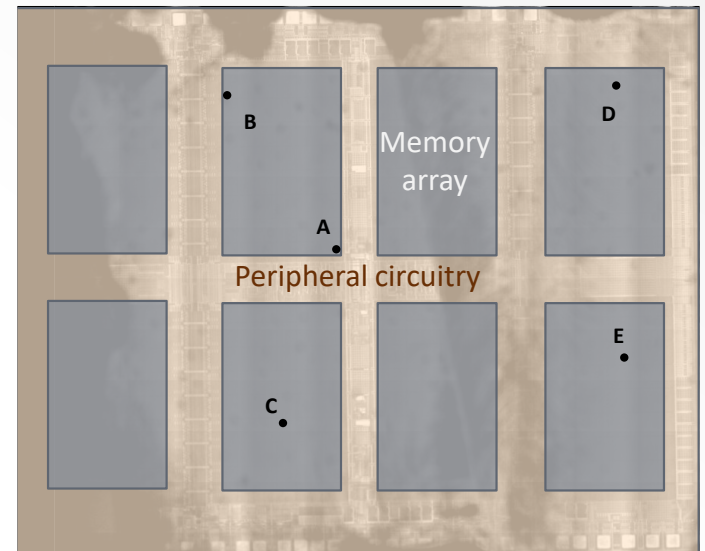
- Test procedure
 - ▶ 5 μm x5 μm scan in the memory array
 - XY step: 0.5 μm
 - Z step: 1 μm from the focus position up to 10 μm above the focus
 - ▶ Increase laser energy (step 10pJ) until a SEU was detected
 - ▶ Measure the laser energy threshold for SEU on different location on the SRAM



Backside laser injection



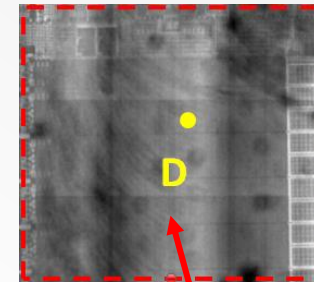
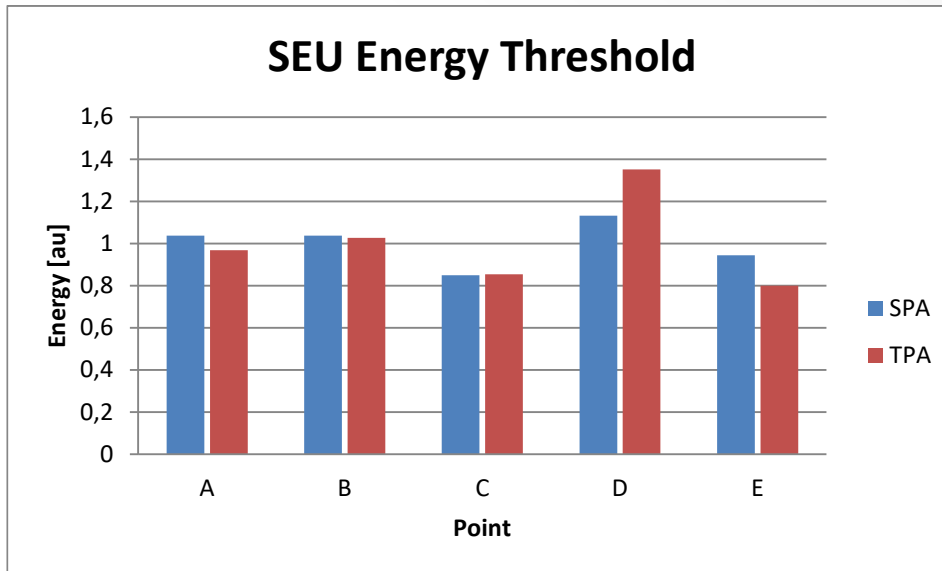
Scanning routine



SRAM structure overview with sensitive points

SRAM: SEU threshold energy results

SEU Threshold energy							
Point	A	B	C	D	E	Mean	STD
SPA (nJ)	0,110	0,110	0,090	0,120	0,100	0,106	11%
TPA (nJ ²)	0,109	0,116	0,061	0,152	0,113	0,113	22%



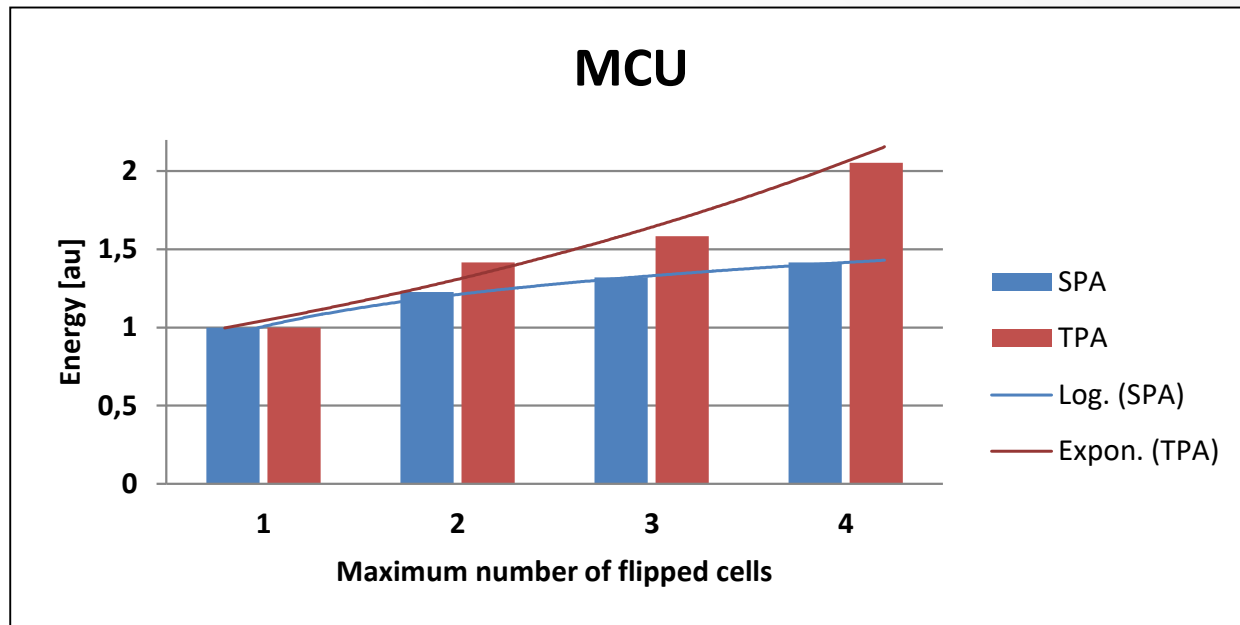
Drilling marks on the backside surface induce laser scattering

- SEU threshold energy variation relative to the location
 - Mainly depend on the backside surface quality
- TPA technic more sensitive to bad backside preparation

SRAM: MCU threshold energy results (1/2)

- By increasing laser energy, several cells flipped

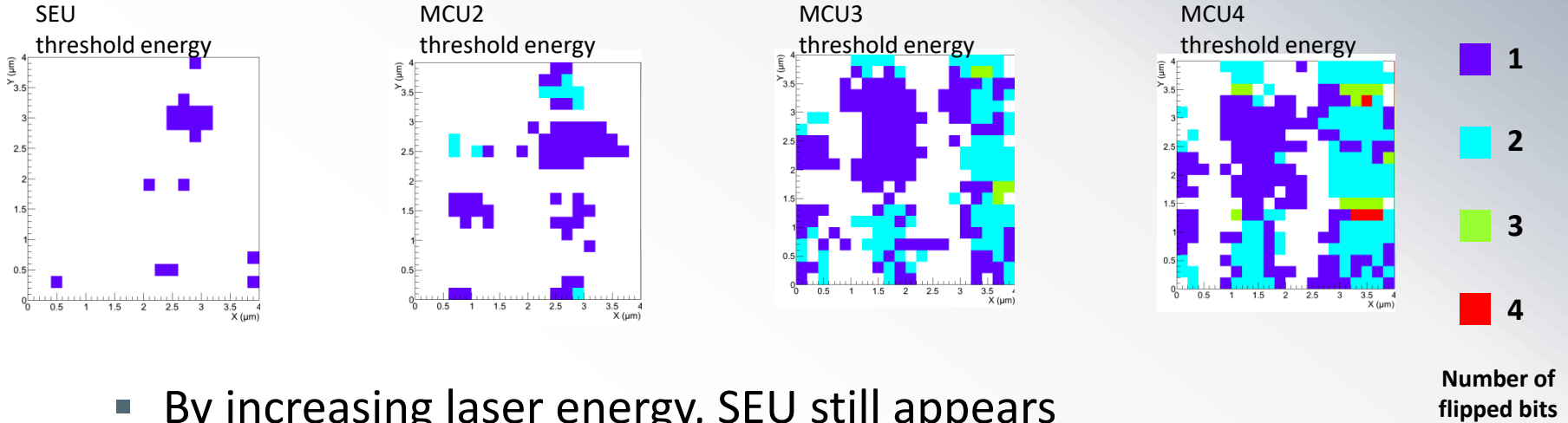
MCU Threshold energy				
Number of flipped cells	1 (SEU)	2	3	4
SPA (nJ)	0,106	0,130	0,140	0,150
TPA (nJ ²)	0,113	0,160	0,179	0,232



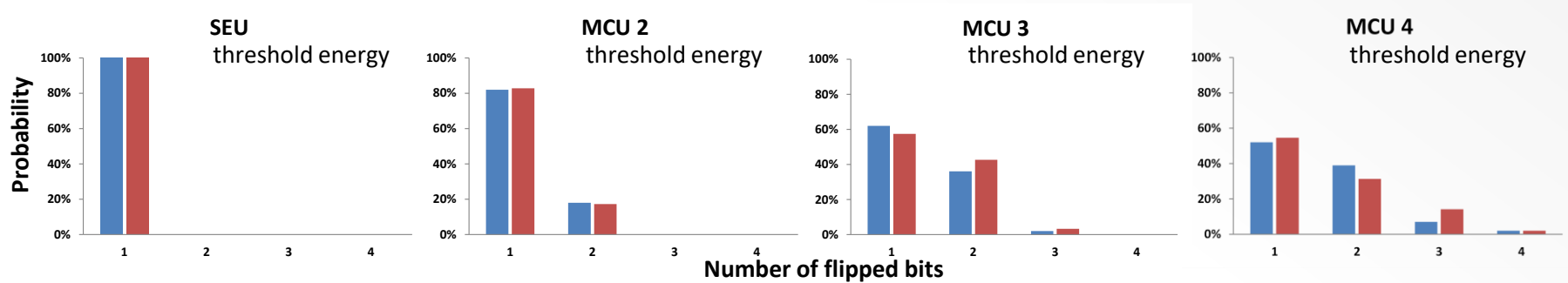
- MCU generation need more energy in TPA



SRAM: MCU threshold energy results (2/2)



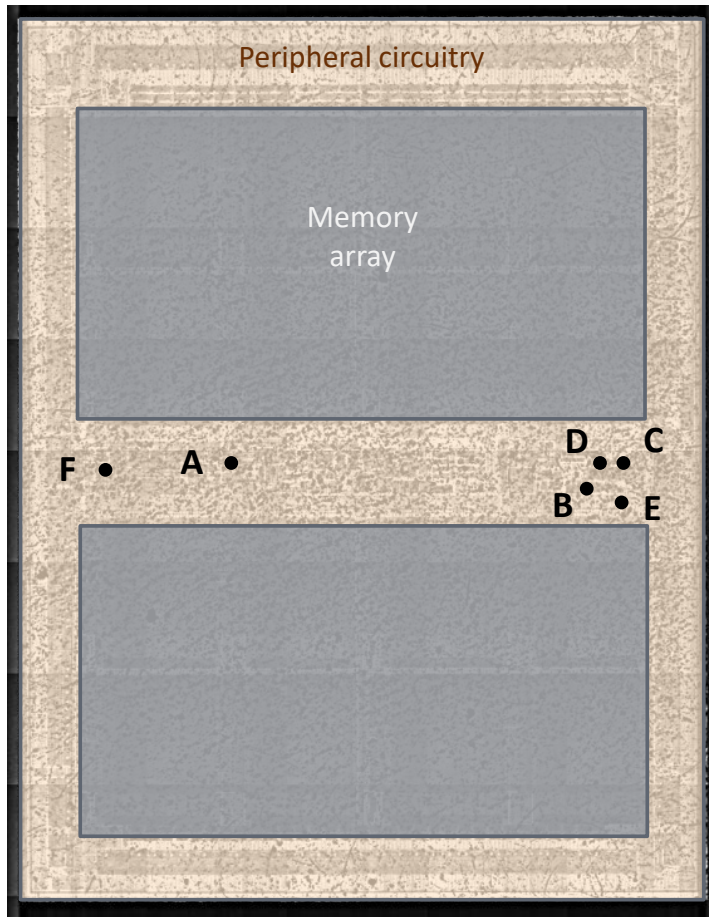
- By increasing laser energy, SEU still appears



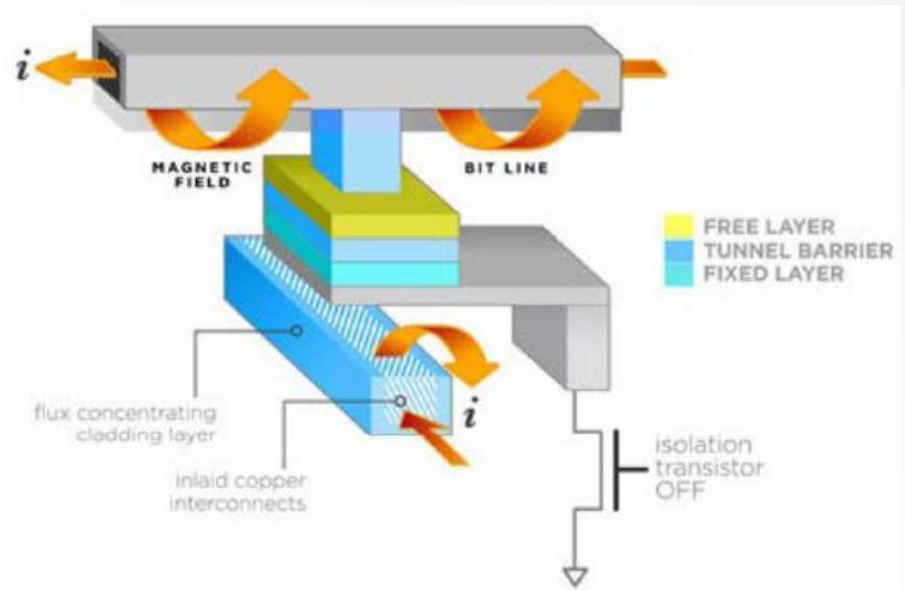
- Probability of MCU apparition with SPA and TPA is very close

MRAM: SEL and SEU threshold energy

- Scan of the peripheral circuitry
- Increase the laser energy until event appears (SEL or SEU)

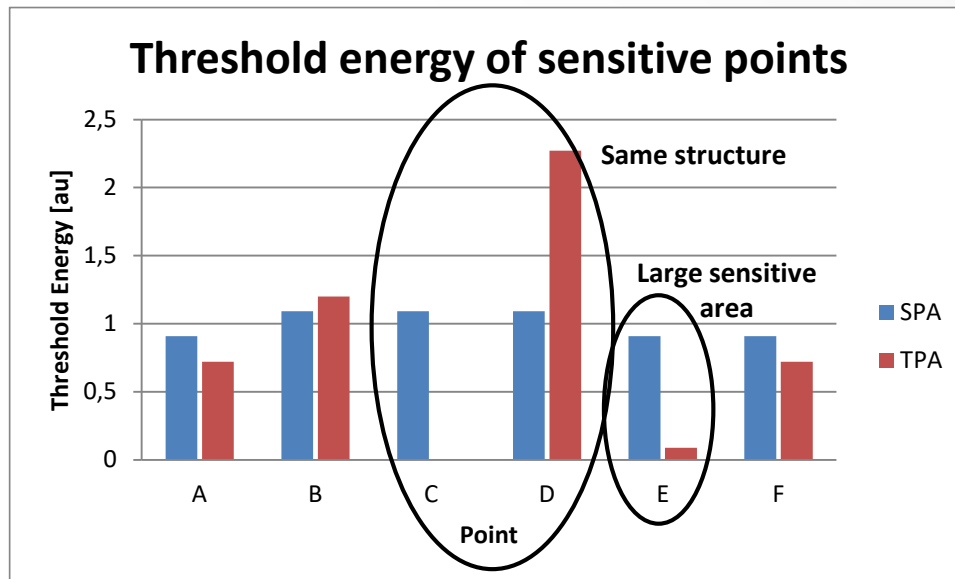
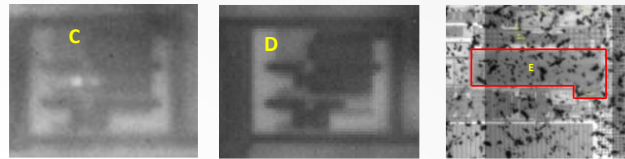


- Magneto-resistive bit cells:
 - Immune to SEE



MRAM: SEL and SEU threshold energy results

Threshold energy						
Point	A	B	C	D	E (zone)	F
Event	SEL	MCU	SEL	SEL	MCU	SEL
SPA (nJ)	0,690	0,828	0,828	0,828	0,690	0,690
TPA (nJ ²)	2,40	4,00	No event	7,57	0,29	2,40





Conclusion

- SEU, MCU and SEL threshold energy was measured on different point on COTS SRAM and MRAM
- Good agreement between SPA and TPA measurements for SEU thresholds on the SRAM
- Some differences observed on specific points of the MRAM probably explained by layout and circuit details
- Threshold energy measurement is more sensitive to backside surface quality with TPA
 - ▶ SPA recommended for scanning large areas
- Future works:
 - ▶ Similar measurements on smaller nodes and correlation with heavy ion data